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Yayi Wei
Tianchun Ye
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Contents

vii Conference Committee

EIGHTH INTERNATIONAL WORKSHOP ON ADVANCED PATTERNING SOLUTIONS (IWAPS 2024)

- 13423 02 **Research on optical proximity correction with embedded coordinate convolution module** [13423-2]
- 13423 03 **EUV lithography imaging modeling and calculation based on full-vector beam propagation method** [13423-3]
- 13423 04 **GAOPC improves OPC parameter search efficiency and convergence speed** [13423-4]
- 13423 05 **A fast method for aerial image blur evaluation** [13423-5]
- 13423 06 **Fast layout pattern matching using spatial indexing** [13423-6]
- 13423 07 **An efficient way towards massive CD-SEM metrology recipes based on line scan analysis: release your hands** [13423-7]
- 13423 08 **Accurate SEM contour-based measurement and analysis of SRAM patterns for enhanced design optimization** [13423-8]
- 13423 09 **Inverse lithography with adaptive threshold regularization** [13423-9]
- 13423 0A **From 1D-spot to 2D-plain: a computer vision-based comprehensive approach for process window qualification** [13423-10]
- 13423 0B **Source-mask co-optimization study for typical EUV design rule patterns with 40nm minimum pitch** [13423-11]
- 13423 0C **Edge placement error analysis through backscattered electron imaging** [13423-13]
- 13423 0D **An effective methodology of filter, measure, and align SEM image in model calibration** [13423-14]
- 13423 0E **SEM contour extraction application on OPC model of contact layer** [13423-15]
- 13423 0F **Inverse lithography based on a physics-driven deep learning approach** [13423-18]
- 13423 0G **Achieving high-accuracy and noise-robust process window analysis through stepwise regression** [13423-19]

- 13423 OH **Fast lithographic source optimization adopting RMSProp with iterative shrinkage-thresholding algorithm compressive sensing for high fidelity patterning** [13423-21]
- 13423 OI **Advancing semiconductor defect detection with integrated deep learning and color scale preprocessing** [13423-22]
- 13423 OJ **Application of path planning in vector scanning electron beam lithography** [13423-25]
- 13423 OK **Multilayer reticle heating impact on product overlay** [13423-26]
- 13423 OL **A fully automatic and generic method for classifying repeating array designs** [13423-27]
- 13423 OM **A study of aerial image NILS and exposure energy as improvement factors for LER** [13423-28]
- 13423 ON **The implementation of overlay compensation between multiple photo layers generated by a single mask** [13423-29]
- 13423 OO **Photolithographic image prediction with conditional adversarial network and parameter encoding** [13423-31]
- 13423 OP **Measurement and analysis algorithm for sub-30 nm patterns of hexagonal arrays in microphotography** [13423-33]
- 13423 OQ **The application of multiple patterning solutions based on process window analysis in lithography** [13423-34]
- 13423 OR **Fresnel diffraction by rectangle aperture: a non-approximate integral theorem and aperture pattern correction** [13423-35]
- 13423 OS **Fast curvilinear optical proximity correction adopting quasi-uniform B-spline curves** [13423-37]
- 13423 OT **Allocation method of micromirror array for deep ultraviolet illumination system** [13423-39]
- 13423 OU **Enabling source and mask optimization by a dynamic aberration imaging model across the full exposure field** [13423-40]
- 13423 OV **Implementation of a versatile and efficient monitoring system in semiconductor high-volume manufacturing** [13423-41]
- 13423 OW **Source-mask co-optimization study for 7 nm metal layer patterns with 80 nm minimum pitch** [13423-42]
- 13423 OX **A hybrid proximity effect correction method based on separation of forward-/back-scattering and cumulative distribution function** [13423-43]
- 13423 OY **Large-scale chip layout pattern clustering method based on graph matching** [13423-44]

- 13423 0Z **Silicon process characterization based on massive SEM contour extraction and hotspot pattern decomposition** [13423-45]
- 13423 10 **Non-destructive measurement of temperature in the micro-area wafer using Mueller matrix spectroscopic ellipsometry** [13423-46]
- 13423 11 **Machine learning based on using layout to generate reference SEM images for defect inspection** [13423-47]
- 13423 12 **Evaluation of hotspots EPE propagation through step-by-step SEM contour analysis** [13423-48]
- 13423 13 **Optical critical dimension accuracy improvement through TEM uncertainty reduction** [13423-52]
- 13423 14 **Advanced computational lithography based on information theory** [13423-53]
- 13423 15 **Wiener-Padé model for lithographic resist modeling** [13423-54]
- 13423 16 **Rigorous simulation for impact of wafer topography on critical dimension** [13423-55]
- 13423 17 **TransUNet-based end-to-end proximity effect correction for electron beam lithography** [13423-56]
- 13423 18 **Evaluation of lithography printability review in mature node photomask manufacturing** [13423-57]
- 13423 19 **Integrated circuit defect classification based on multi-layer attention mechanisms** [13423-58]
- 13423 1A **Frequency-domain modeling-free learning control for wafer stages with transient improvement by adaption** [13423-59]
- 13423 1B **Study on EUV mask blank inspection with multi-wavelength high harmonic generation EUV source** [13423-60]
- 13423 1C **Study on interaction between bottom SiARC and photoresist** [13423-62]
- 13423 1D **Investigation of mask thickness effects and their significance for the 28nm node and beyond** [13423-63]
- 13423 1E **Thermal microscopic imaging based on diffusion models for super-resolution inspection** [13423-66]
- 13423 1F **Development of a synchrotron-based EUV microscope for actinic mask inspection** [13423-67]
- 13423 1G **Lithography vacuum and exhaust gas management for EUV high NA** [13423-72]

- 13423 1H **Customized metrology target design to address OPO challenges** [13423-73]
- 13423 1I **A methodology for random placement of unit patterns to identify potential design and process optimizations** [13423-74]
- 13423 1J **SONR-based gauge down sampling for OPC modeling** [13423-75]
- 13423 1K **Zernike polynomial-based pupil wavefront optimization technology for extreme ultraviolet lithography** [13423-78]
- 13423 1L **A method of combing optical proximity correction and design layout optimization to improve process window** [13423-80]
- 13423 1M **Influence of sidewall affinity on the directed self-assembly for contact hole multiplication** [13423-81]
- 13423 1N **Method for improving overlay accuracy** [13423-82]
- 13423 1O **Quadruple-hole multiplication by directed self-assembly of block copolymer** [13423-83]
- 13423 1P **Integration of deep learning for nonlinear spectral decomposition of in situ interfaces analysis** [13423-85]